

07-29-2002



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OVER SHEET
LY

U.S. DEPARTMENT OF COMMERCE

Patent and Trademark Office

To the Assistant Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereon.

1. Name of conveying party(ies):

(1) MING HUNG CHOU
(2) TU SHUN CHEN
(3) SMILE HUANG

2. Name and address of receiving party(ies):

Macronix International Co., Ltd.
No. 16, Li-Hsin Road
Science-Based Industrial Park
Hsinchu, Taiwan, R.O.C.

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Additional name(s) & address(es) attached?

☐ Yes ☒ No

Execution Date: (1) 4 JULY 2002; (2) 8 JULY 2002;
(3) 6 JULY 2002

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: (1) 4 JULY 2002;
(2) 8 JULY 2002; (3) 6 JULY 2002

A. Patent Application No.(s):

B. Patent No.(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Mark A. Haynes, Esq.
Haynes Beffel & Wolfeld LLP
P.O. Box 366
Half Moon Bay, CA 94019

6. Total number of applications and patents involved: [1]

7. Total fee (37 CFR 3.41) \$40.00
☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit account number: 50-0869
(Attorney Docket No.: MXIC 1530-1)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mark A. Haynes, Reg. No. 30,846
Typed Name, Registration Number

Signature

15 July 2002
Date

Total number of pages including cover sheet, attachments and document: [4]

ASSIGNMENT
(Joint to Corporate)

WHEREAS, the undersigned,

- | | |
|--|---|
| <p>(1) Ming Hung CHOU
No. 31-5, Dong Ming Li,
Houlung Jen, Miaoli,
Taiwan 356, R.O.C.</p> | <p>2) Tu Shun CHEN
No. 130, Wutsuo Li,
Shiluo Jen, Yunlin,
Taiwan 648, R.O.C.</p> |
| <p>(3) Smile HUANG
No. 24, Alley 75, Lane 112,
Chengbei Rd. Annan Chiu,
Tainan, Taiwan 709, R.O.C.</p> | |

hereinafter termed "Inventors", have invented certain new and useful improvements in

**PLASMA DAMAGE PROTECTION CIRCUIT
FOR A SEMICONDUCTOR DEVICE**

and have filed an application for a United States patent disclosing and identifying the above invention on _____ as Application No. _____, OR are filing such an application herewith, and have executed an oath or declaration of inventorship for such application on:

- (1) the 4th day of July, 2002;
- (2) the 8th day of July, 2002;
- (3) the 6th day of July, 2002;

(hereinafter termed "application"); and

WHEREAS, **Macronix International Co., Ltd.**, a corporation of Taiwan, having a place of business at No. 16, Li-Hsin Road, Science-Based Industrial Park, Hsinchu, Taiwan R.O.C. (hereinafter termed "Assignee"), is desirous of acquiring the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter termed "patents") thereon granted in the United States and foreign countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey unto said Assignee the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply for foreign patents on said invention pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all applications filed and any and all patents granted on said invention in the United States or any foreign country, including each and every application filed and each and every patent granted on any application which is a divisional, substitution, continuation, or continuation-in-part of any of said applications; and (d) in and to each and every reissue or extensions of any of said patents.

2. Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and foreign countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (d) for filing and prosecuting applications for reissuance of any said patents; (e) for interference or other priority proceedings involving said invention; and (f) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation reissues and reexaminations, opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.

4. Said Inventors hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, said Inventors have executed and delivered this instrument to said Assignee as of the dates written below.

Ming Hung Chou
Ming Hung CHOU

2002. 7. 4.
Dated:

Tu Shun Chen
Tu Shun CHEN

2002. 7. 8
Dated:

Smile Huang
Smile HUANG

2002. 7. 8
Dated: